

SLOVENSKI STANDARD SIST EN 62496-2-2:2011

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Plošče z optičnimi vezji - Preskusni in merilni postopki - 2-2. del: Meritve: Mere plošč z optičnimi vezji (IEC 62496-2-2:2011)

Optical circuit boards - Test and measurement procedures - Part 2-2: Measurements: Dimensions of optical circuit boards (IEC 62496-2-2:2011)

Optische Leiterplatten - Prüf- und Messverfahren - Teil 2-2: Messverfahren - Abmessungen optischer Leiterplatten (IEC 62496-2-2:2011)

Cartes à circuits optiques - Partie 2-2: Mesures - Dimensions des cartes à circuits optiques (CEI 62496-2-2:2011) https://standards.iteh.ai/catalog/standards/sist/ae08d2b4-cbaa-4002-8d64-3db0ce41e3af/sist-ep-62496-2-2-2011 Ta slovenski standard je istoveten z: EN 62496-2-2:2011

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
33.180.01	Sistemi z optičnimi vlakni na splošno	Fibre optic systems in general

SIST EN 62496-2-2:2011

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EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

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ICS 33.180.01

English version

Optical circuit boards -Part 2-2: Measurements -Dimensions of optical circuit boards (IEC 62496-2-2:2011)

Cartes à circuits optiques -Partie 2-2: Mesures -Dimensions des cartes à circuits optiques (CEI 62496-2-2:2011) Optische Leiterplatten -Teil 2-2: Messungen -Abmessungen optischer Leiterplatten (IEC 62496-2-2:2011)

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CENELEC

European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

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Foreword

The text of document 86/378/FDIS, future edition 1 of IEC 62496-2-2, prepared by IEC TC 86, Fibre optics, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62496-2-2 on 2011-03-03.

The following dates were fixed:

-	latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2011-12-03
-	latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2014-03-03

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62496-2-2:2011 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60793-2	NOTE	Harmonized as EN 60793-2.	
IEC 62496 series	NOTE	Harmonized in EN 62496 series.	
		SIST EN 62496-2-2:2011	

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Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	<u>EN/HD</u>	Year
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60793-1-45 (mod)	-	Optical fibres - Part 1-45: Measurement methods and test procedures - Mode field diameter	EN 60793-1-45	-
IEC 61189-2	-	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2: Test methods for materials for interconnection structures	EN 61189-2	-
IEC 62496-2-1	- iT	Optical circuit boards - Basic test and measurement procedures - Part 2-1: Measurements - Optical attenuation and isolation	FprEN 62496-2-1	-
IEC 62496-4	https://sta	Optical circuit boards ^{496-2-2:2011} Part 4: Interface standards ^{t/a} General and ⁴⁰⁰ guidance ^{ce41e3af/sist-en-62496-2-2-2011}	FprEN 62496-4 2-8d64-	-
ISO 10360-2	-	Geometrical product specifications (GPS) - Acceptance and reverification tests for coordinate measuring machines (CMM) - Part 2: CMMs used for measuring linear dimensions	EN ISO 10360-2	-

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NORME INTERNATIONALE



Optical circuit boards h STANDARD PREVIEW Part 2-2: Measurements – Dimensions of optical circuit boards

Cartes à circuits optiques – <u>SIST EN 62496-2-2:2011</u> Partie 2-2: Mesures star Dimensions des cartes à circuits optiques 3db0ce41e3af/sist-en-62496-2-2-2011

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Table 1 – Objects to be measured and their methods......7

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

OPTICAL CIRCUIT BOARDS -

Part 2-2: Measurements – Dimensions of optical circuit boards

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The text of this standard is based on the following documents:

FDIS	Report on voting
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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62496 series, published under the general title *Optical circuit boards*, can be found on the IEC website.

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OPTICAL CIRCUIT BOARDS –

Part 2-2: Measurements – Dimensions of optical circuit boards

1 Scope

This part of IEC 62496 specifies the measurement procedures for dimensions related to interface information of optical circuit boards (OCB), defined in IEC 62496-4.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1, Environmental testing – Part 1: General and guidance

IEC 60793-1-45, Optical fibres – Part 1-45: Measurement methods and test procedures – Mode field diameter

IEC 61189-2, Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2: Test methods for materials for sister connection structures SIST EN 62496-2-2:2011

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IEC 62496-2-1, Optical circuit boards⁴ Part 2¹ Measurements – Optical attenuation and isolation¹

IEC 62496-4, Optical circuit boards – Part 4: Interface standards – General and guidance

ISO 10360-2, Geometrical product specifications (GPS) – Acceptance and reverification tests for coordinate measuring machines (CMM) – Part 2: CMMs used for measuring linear dimensions

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

3.1

optical position adjusting system

consists of a light source, fibre position adjustment stage, OCB holder, input/output fibre and a power meter. The optimum fibre launch position, at which the optical output power is maximised, is determined through alignment of the input/output fibres to the OCB and monitoring the output power from the OCB

3.2

dimensional drawing

illustration, including dashed lines, which defines classified OCB or OCB body shape accuracy using the origin point or alignment mark as the standard point

¹ To be published.